HONGLITRONIC
鸿利光电

Specification

规 格 书

Customer Name _____
客户名称

Customer P/N _____
客户品号

Factory P/N _____
公司品号

Sending Date _____
送样日期

Client approval 客户审核			Hongli approval 鸿利光电审核		
Approval 核准	Audit 确认	Confirmation 制作	Approval 核准	Audit 确认	Confirmation 制作
			林德顺		黄雪梅
□ Qualified 接受		□ Disqualified 不接受	DATE: 日期:		

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2.
3. , , ,

The White LED which was fabricated using a blue chip and the phosphor

LED

■ Optical indicator

■ Indoor display

■ Automotive lighting

■ Backlight for LCD, switch and Symbol, display

LCD

■ Tubular light application

■ General use

Notes:

1. All dimension units are millimeters.

2.All dimension tolerance is ±0.15mm unless otherwise noted. ±0.15mm

Part No.	Chip Materials	Lens Type
HL-A-2835D49W-2C-S1-08-PCT-HR3	InGaN	Yellow Diffused

Part No.	CCT K Min	CCT K Typ	CCT K Max	Φ lm Min	Φ lm Typ	Test Condi-tions
HL-A-2835D49W-2C-S1-08-PCT-HR3	5700	6000	6500	120	130	IF=150mA
	4750	5000	5300	120	130	IF=150mA
	3800	4000	4250	120	130	IF=150mA
	2800	3000	3100	110	120	IF=150mA

Parameter	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Forward Voltage	VF	5.6	- -	6.8	V	IF=150mA
Viewing Angle	2θ1/2	- -	120	- -	deg	IF=150mA
Color Rendering Index	Ra	80	- -	- -		IF=150mA

Note:(

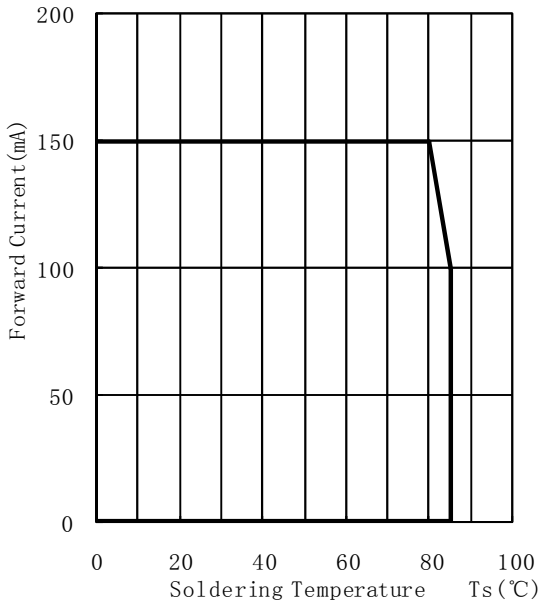
1. 2θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
   2θ1/2 , 1/2
2. The above luminous flux measurement allowance tolerance is ±10%.
   ±10%
3. The above Color Rendering Index measurement allowance tolerance is ±2
   ±2
4. The above forward voltage measurement allowance tolerance is ±0.1V.
   ±0.1V
5. The above color coordinates measurement allowance tolerance is ±0.003.
   ±0.003

Parameter	Symbol	Rating	Units
Power Dissipation	Pd	1020	mW
Forward Current	IF	150	mA
Peak Forward Current [1]	IFP	200	mA
Electrostatic Discharge (HBM)	ESD	1000	V
Operating Temperature	Topr	-40 ~ +85	
Storage Temperature	Tstg	-40 ~ +100	
Thermal Resistance Junction / Soldering point	Rthj-s	15	/W
Junction Temperature	Tj	115	

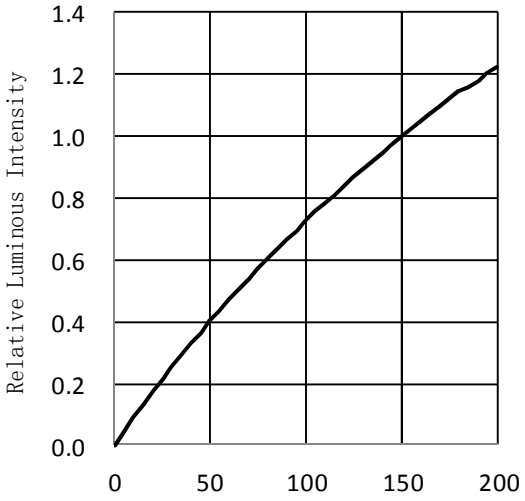
Note:

1. 1/10 Duty cycle, 0.1ms pulse width. 0.1ms, 1/10

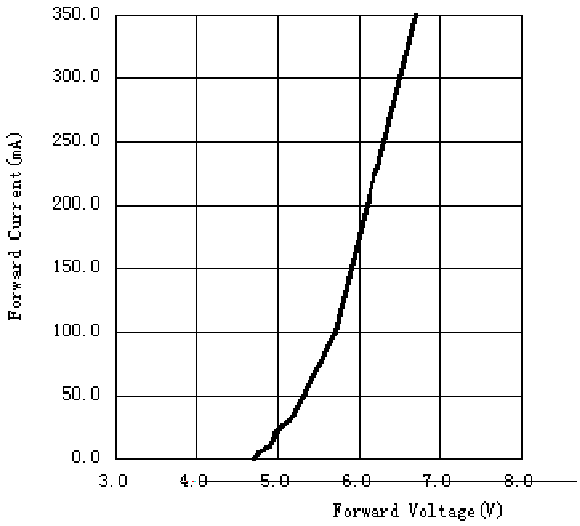
Soldering Temperature vs. Forward Current



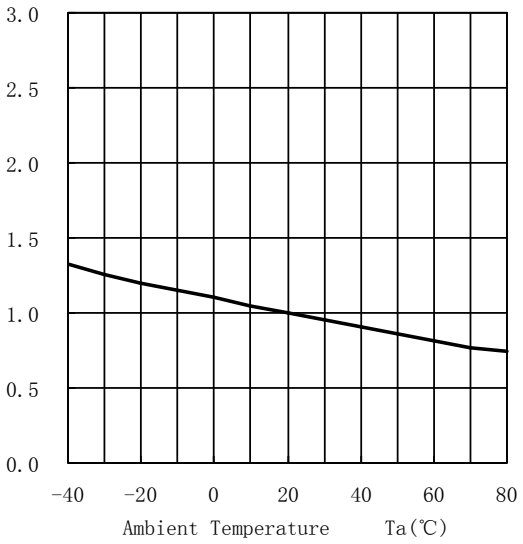
Forward Current VS. Relative Intensity

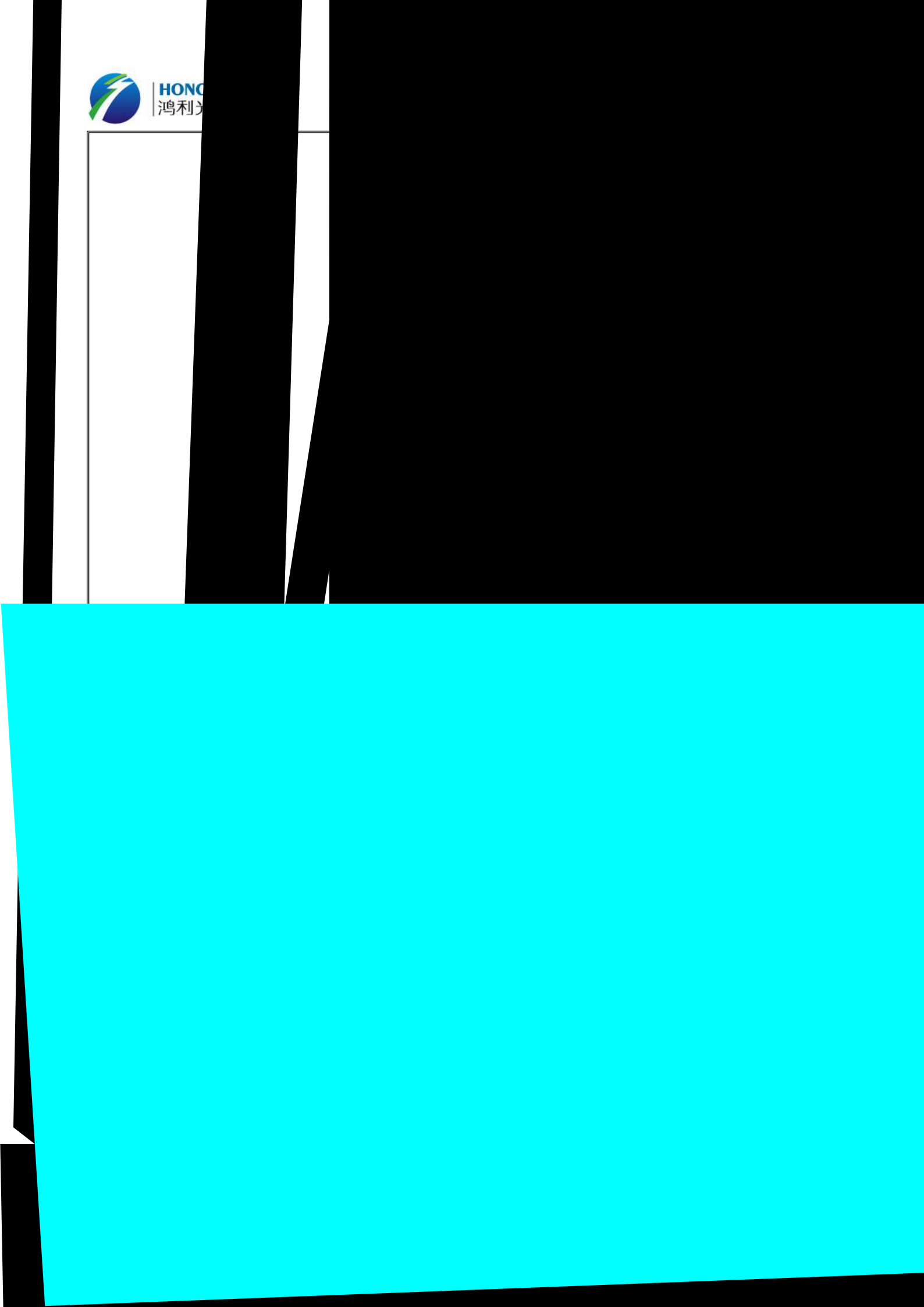


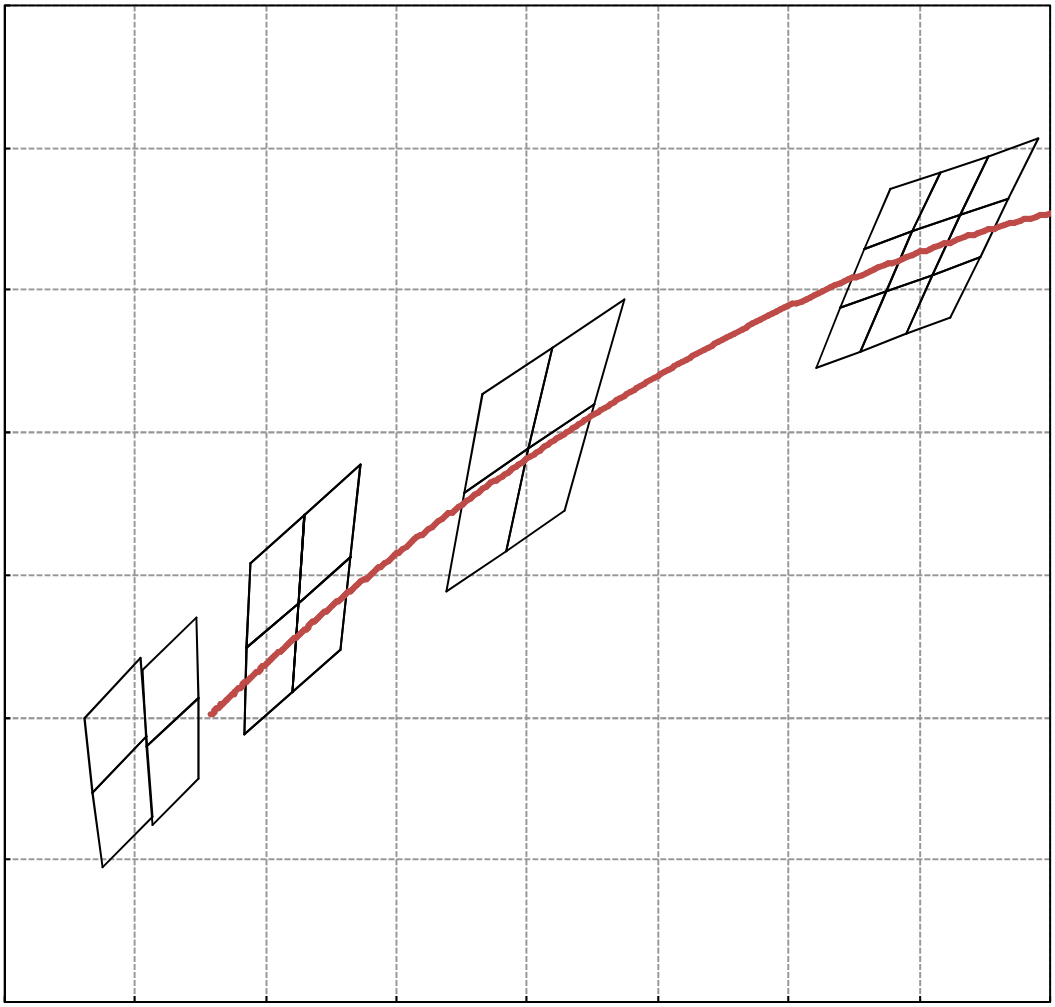
Forward Voltage VS. Forward Current



Ambient Temperature VS. Relative Intensity

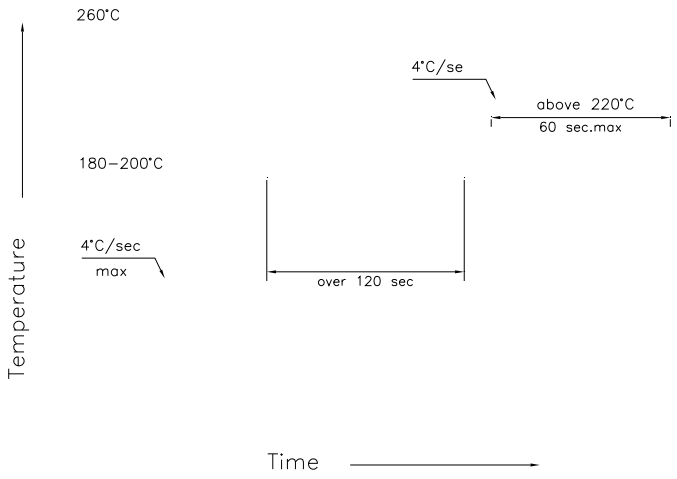






Bin

CCT	Bin Code Bin	CIE_x	CIE_y	Bin Code Bin	CIE_x	CIE_y
3000K	W42 3000-3100K	0.4354	0.4142	W43 3000-3100K	0.4316	0.4059
		0.4430	0.4165		0.4390	0.4082
		0.4390	0.4082		0.4350	0.3998
		0.4316	0.4059		0.4279	0.3975
	W44 3000-3100K	0.4279	0.3975	W52 2900-3000K	0.4430	0.4165
		0.4350	0.3998		0.4505	0.4189
		0.4310	0.3915		0.4463	0.4106
		0.4241	0.3892		0.4390	0.4082
	W53 2900-3000K	0.4390	0.4082	W54 2900-3000K	0.4350	0.3998
		0.4463	0.4106		0.4420	0.4022
		0.4420	0.4022		0.4378	0.3939
		0.4350	0.3998		0.4310	0.3915
	W62 2800-2900K	0.4505	0.4189	W63 2800-2900K	0.4463	0.4106
		0.4581	0.4212		0.4536	0.4129
		0.4536	0.4129		0.4492	0.4045
		0.4463	0.4106		0.4420	0.4022
	W64 2800-2900K	0.4420	0.4022			
		0.4492	0.4045			
		0.4447	0.3962			
		0.4378	0.3939			


260°C
4°C/se
above 220°C
60 sec.max
180–200°C
4°C/sec
max
over 120 sec
Temperature
Time

1.Handle the component along the si by ng forceps or appropriate tools; do not directly touch or Handle the silicone lens sur da ge the internal circuitry.